## COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

## CHIP PACKAGE STRUCTURE AND PROCESS FOR FABRICATING THE SAME

the specification of	which					
<ul><li>_X is attached he</li><li>_ was filed on _</li><li>as Application</li></ul>		aı	nd was an	nended on		
specification, includ I acknowledge application in accor	ing the claim the duty to d dance with Ti foreign prices for patent of tion for pate	s, as amer disclose in tle 37, Coo ority benef or inventor nt or inver	nded by ar formation de of Fede its under s certifica	which is material teral Regulations, § Title 35, United Stellisted below and	erred to above. o the patental 1.56(a). tates Code, § have also ide	oility of this 119 of any ntified below
Number	Country		Date Filed(yyyy/mm/dd)		Yes	No
2003-117506	Japan		2003/4/22		X	
92129523	Taiwan, R.O.C.		2003/10/24		X	
I hereby appoint the transact all business  Belinda Legares Jiawei Hua  Charles C.I	s in the Pater e ng	•	lemark Of . 46,863) . 43,330)	, .		
SEND CORRESPONDENCE TO:				DIRECT TELEPHONE CALLS TO: (Name and Telephone Number)		
JIANQ CHYUN Intellectual Property Office 7F1, No. 100, Roosevelt Rd., Sec. 2, Taipei 100, Taiwan, R.O.C. TEL: 886-2-2369 2800				Ве	linda Lee	

FAX: 886-2-2369 7233

## COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: Ka; - Ch: Chen	Date: Oct. 29, 2003					
Sole or First Joint Inventor: Kai-Chi Chen						
Citizenship: Taiwan, R.O.C.						
Residence and Post Office Address: No.269, Jhongjhe Taiwan R.O.C.	eng Rd., Caotun Township, Nantou County 542,					
Signature: Shu-Chen Huang	Date: 0ct. 2f , 2003					
Second Joint Inventor (if any): Shu-Chen Huang						
Citizenship: Taiwan, R.O.C.						
Residence and Post Office Address: 6F1, No.66, Jhongsing Rd., Sinyi District, Keelung City 201, Taiwan R.O.C.						
Signature: HSUN-Tion Li Third Joint Inventor (if any): Hsun-Tien Li	Date: Oct . 29 , 2003					
Citizenship: Taiwan, R.O.C.						
Residence and Post Office Address: 5F., No.177, Sinjhuang St., Hsinchu City 300, Taiwan R.O.C.						
Signature: Trong Ming Lee	Date: 0.7.29.2003					
Fourth Joint Inventor (if any): Tzong-Ming Lee						
Citizenship: Taiwan, R.O.C.						
Residence and Post Office Address: No.18, Jinshanbei2 St, Hsinchu City 300, Taiwan R.O.C.						
Signature: 7. Julian	Date: $0 + 2f.2003$					
Fifth Joint Inventor (if any): Taro FUKUI						
Citizenship: Japan						
Residence and Post Office Address: 5-10-8, Hirano Ho	nmachi, Hirano-Ku, Osaka, Japan					
Signature: Jr, Memotia	Date: 006. 29 2003					
Sixth Joint Inventor (if any): Tomoaki NEMOTO	7					
Citizenship: Japan						

Residence and Post Office Address: 11-23, Narita Minamimachi, Neyagawa-Shi, Osaka, Japan